Circuit Pattern: Pad-Per-Hole Contacts: N/A Width/Thick: 12.86"/.062" Height: 4.00" Contacts: N/A

16-Pin DIP Capacity: 124

Material: FR4 Epoxy Glass Wire-Wrap Terminals: T44, T46, T49, T68,

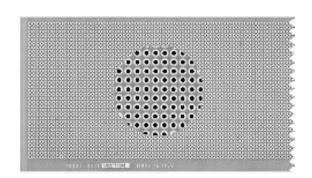
Solder Terminals: T42-1 Wire-Wrap Socket Pins: R32 Hole Diameter: .042"

· Precision-Drilled, plated-thru holes

0.080" diameter, isolated solder pad around each hole

Board size and surface area approximate Macintosh II specifications

Unrestricted component placement



### 8001 4.50" x 6.5"

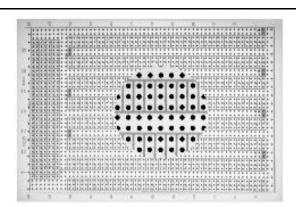
Circuit Pattern: 3-Hole Solder Pad

Contacts: N/A Width/Thick: 6.50"/.062" Height: 4.50" 16-Pin DIP Capacity: 20 Material: CEM-1

**Solder Terminals:** T42-1, K24C, K31C Wire-Wrap Terminals: T44, T46, T49, T68

Wire-Wrap Socket Pins: R32 Hole Diameter: .042'

- Circuit pattern etched onto wiring side only
- Solder mount DIP sockets or IC devices with any lead spacing
- 3-hole solder pads (0.28" X 0.080") for interconnecting multiple component leads



### 8002 4.5" x 6.5"

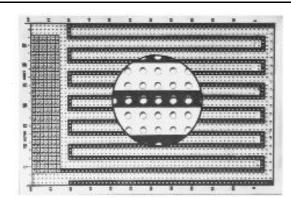
Circuit Pattern: Interleaved Buses Contacts: Width/Thick: 6.50"/.062" 4.50" Height: 16-Pin DIP Capacity: 36

Material: CEM-1 **Solder Terminals:** T42-1

Wire-Wrap Terminals: T44, T46, T49, T68

Wire-Wrap Socket Pins: R32 Hole Diameter: 042'

- Ideal for wire-wrap applications
- Power and ground buses etched onto wiring side only
- Bus surfaces solder coated for user convenience
- Mount components with 0.3", 0.6" and 0.9" lead spacina
- I/O area with solder pads for mounting connector



### 8003 4.5" x 6.5"

Circuit Pattern: Pad-Per-Hole Contacts: N/A

6.50"/.062" Width/Thick: Height: 4.50" 16-Pin DIP Capacity: 60 Material: CEM-1

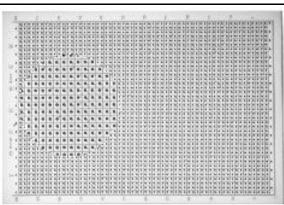
Wire-Wrap Terminals: T44, T46. T49. T68

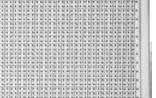
T42-1

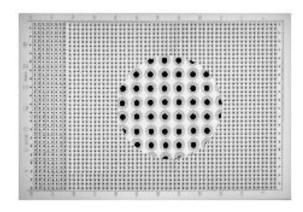
Wire-Wrap Socket Pins: R32 Hole Diameter: .042"

Solder Terminals:

- · Square solder pad etched around each hole on wiring side
- Accommodates any type DIP IC device or discrete component







### 4.5" x 6.5" 8004

Circuit Pattern: Ground Plane Contacts: N/A 6.50"/.062" Width/Thick: Height: 4.50" 16-Pin DIP Capacity: 50 Material: CEM-1 **Solder Terminals:** T42-1

Wire-Wrap Terminals: T44, T46, T49, T68 • Wire-Wrap Socket Pins: R32

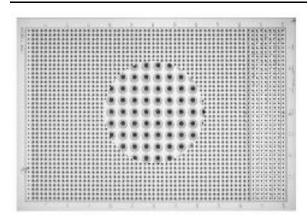
Hole Diameter: .042" To commit wire-wrap pins to voltage and ground planes, use Vector T124 solder washers, available separately

0.085" diameter clearance around holes

Etched overall ground plane on wiring side only

Plane surfaces solder-coated for user convenience

I/O area with solder pads for mounting connector



### 4.5" x 6.5" 8007

Pad-Per-Hole/

Circuit Pattern:

Ground Plane N/A Contacts: Width/Thick: 6.50"/.062" Height: 4.50" 16-Pin DIP Capacity: 60

Material: CEM-1 **Solder Terminals:** T42-1

Wire-Wrap Terminals: T44, T46, T49, T68 • Wire-Wrap Socket Pins: R32 Hole Diameter: .042"

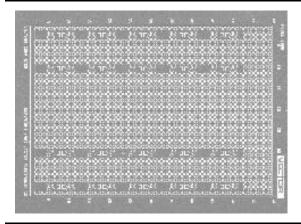
Pad-Per-Hole pattern on component side - overall Ground Plane pattern on wiring side

To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately

 0.080" diameter, isolated solder pad around holes, component

Accommodates any type DIP IC device or discrete component

Plane and pad surfaces soldercoated for user convenience



## 8008

4.5" x 6.5" Circuit Pattern: Pads & Planes

Contacts: N/A Width/Thick: 6.50"/.062" Height: 4.50" 16-Pin DIP Capacity: 70

Material: FR4 Epoxy Glass **Solder Terminals:** T42-1

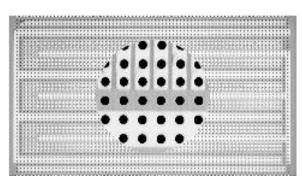
Wire-Wrap Terminals: T44, T46, T49, T68 Wire-Wrap Socket Pins: R32 Hole Diameter: .042"

· Unique circuit pattern features full voltage and ground planes on opposite sides with isolated, plated-thru holes

0.080" diameter, isolated solder pad around holes, component side

Plane surfaces solder-coated for user convenience

SMD cap positions for discrete decoupling capacitors



## 3677-6

4.5" x 8.08"

Circuit Pattern: 3-Hole Solder Pad Contacts: N/A Width/Thick: 8.08"/.062" Height: 4.50" 16-Pin DIP Capacity: 21 Material: CEM-1 Solder Terminals: T42-1 Wire-Wrap Terminals:

T44, T46, T49, T68 • Wire-Wrap Socket Pins: R32

Hole Diameter: .042" • Etched circuit pattern on wiring side only

0.080" diameter, isolated solder pad around holes, both sides

3-hole solder pads (0.028" X 0.080") for interconnecting multiple component leads

Pad and bus surfaces soldercoated for user convenience



### 4.5" x 8.08" 45P80-1

Circuit Pattern: Pad-Per-Hole

Contacts: N/A

Width/Thick: 8.08"/.062" Height: 4.50"

16-Pin DIP Capacity: 80 Material: CEM-1 **Solder Terminals:** T42-1

Wire-Wrap Terminals: T44, T46, T49, T68

Wire-Wrap Socket Pins: R32 Hole Diameter: .042"

### 5.0" x 13.25" 8006

Circuit Pattern: Pad-Per-Hole

Contacts: N/A Width/Thick: 13.25"/.062" Height: 5.00"

16-Pin DIP Capacity: 154

Material: FR4 Epoxy Glass

**Solder Terminals:** T42-1

Wire-Wrap Terminals: T44, T46, 49, T68

Wire-Wrap Socket Pins: R32 Hole Diameter: .042'

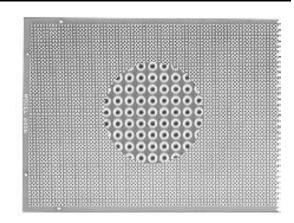
- · Copper plated-thru holes
- 0.080" diameter, isolated solder pad around holes, both sides

· Isolated, square pads around

each hole

- Unrestricted component place ment, extended area for high density applications
- Board can be cut down into

smaller units



### 9.2" x 11.0" 8012

Pad-Per-Hole Circuit Pattern: Contacts: N/A Width/Thick: 11.00"/.062"

16-Pin DIP Capacity: 283

Height:

Material: FR4 Epoxy Glass

**Solder Terminals:** T42-1 Wire-Wrap Terminals: T44, T46, T49, T68

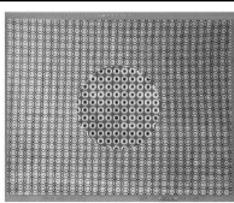
9.20"

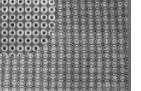
Wire-Wrap Socket Pins: R32 Hole Diameter: .042' · Plated-thru holes

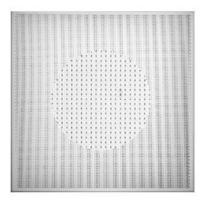
Approximates Eurocard (DIN) specifications: 6Ux280MM, can be sheared down to 6U x 220MM, or 160MM

0.080" diameter, isolated solder pad around holes

Unrestricted component placement, extended area for high density applications







## 106P106-1 10.6" x 10.6"

Circuit Pattern: Pad-Per-Hole Contacts: N/A

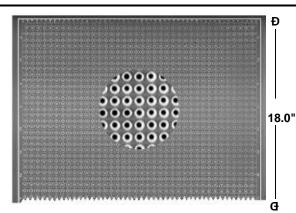
Width/Thick: 10.60"/.062" Height: 10.60"

16-Pin DIP Capacity: 275

Material: FR4 Epoxy Glass Solder Terminals: T42-1

**Wire-Wrap Terminals:** T44, T46, T49, T68

Wire-Wrap Socket Pins: R32 Hole Diameter: .042"



# 106P180-4 10.6" X 18.0"

Circuit Pattern: Pad-Per-Hole & Ground Plane,

2 sides

Contacts: N/A

Width/Thick: 10.60"/.062"

**Height:** 18.00 **16-Pin DIP Capacity:** 400

Material: FR4 Epoxy Glass Solder Terminals: T42

Wire-Wrap Terminals: T44, T46, T49,T68

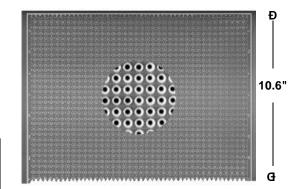
Wire-Wrap Socket Pins: R32 Hole Diameter: .042"  Individual pads with plated-thru holes

· 0.080" diameter, isolated solder

pad around each hole, both sides

- Etched ground plane surrounds pads on both sides
- 0.080" diameter, isolated solder pad around each hole, both sides

## 106P70-4 7.0" x 10.6"



Circuit Pattern: Pad-Per-Hole & Ground Plane
Contacts: N/A

Width/Thick: 7.0"/.062"
Height: 10.60"
16-Pin DIP Capacity: 175

Material: FR4 Epoxy Glass 2 sides

Solder Terminals: T42-1 Wire-Wrap Terminals: T44, T46, T49, T68

Wire-Wrap Socket Pins: R32 Hole Diameter: .042"

- Individual pads with plated-thru holes
- Etched ground plane surrounds pads on both sides
- 0.080" diameter, isolated solder pad around each hole, both sides

